CLIPPEDIMAGE= JP359105349A

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TITLE: INTEGRATED CIRCUIT DEVICE

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INVENTOR-INFORMATION:
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NAME	COUNTRY
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ABSTRACT:

PURPOSE: To enable to manufacture an integrated circuit substrate which has
many terminals and complicated functions with a small area and good yield at a
low cost by a method wherein electrode terminals on the integrated circuit
substrate are so arranged that the interval between connection members becomes
almost constant.

CONSTITUTION: A pad d<SB>7</SB> is set at the center of one side. Next, the
value of a wire interval l is set at a value which satisfies the condition of
wire bonding, pads d<SB>5</SB> and d<SB>8</SB> are decided by drawing a

triangle whose bottom side is a wire C<SB>7</SB> and height is l. Further, pads
d<SB>5</SB> and d<SB>9</SB> are decided by drawing a triangle whose bottom side
is wires C<SB>6</SB> and C<SB>8</SB> and height is l. The pads
d<SB>1</SB>∼d<SB>13</SB> are arranged in the above-mentioned manner, the
value of the interval l is set again by evaluating its result, and the optimum
arrangement is made by successive approximation with a computer. For example,
the arrangement of 13 bonding pads
d<SB>1</SB>∼d<SB>13</SB> is made on one
side of a chip, and, based on the optimum value, the pad intervals are
successively enlarged toward each corner from the center of one side of the
chip; thereby enabling the arrangement in such a manner that each wire interval
becomes almost constant.